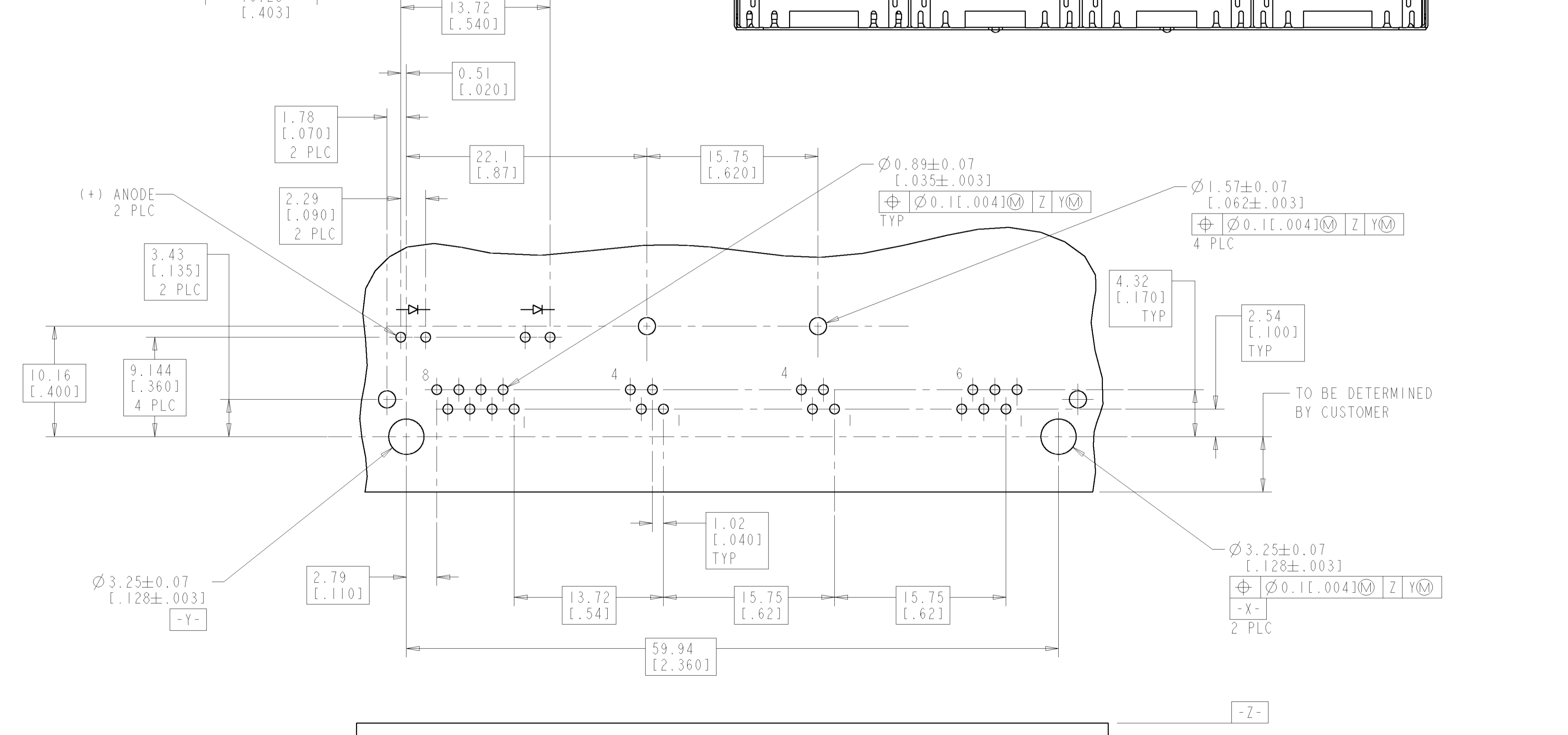
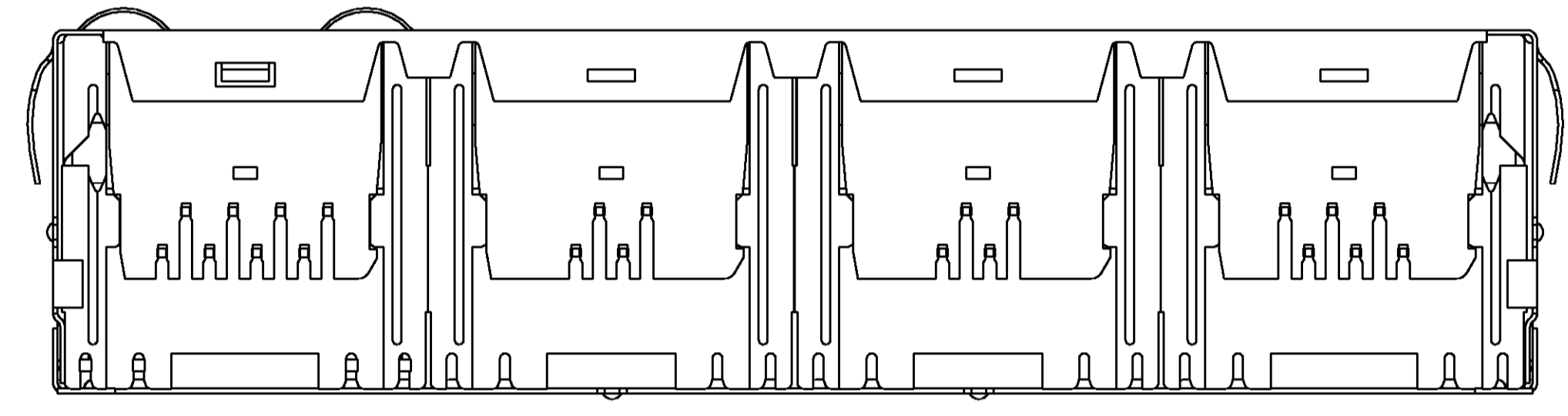
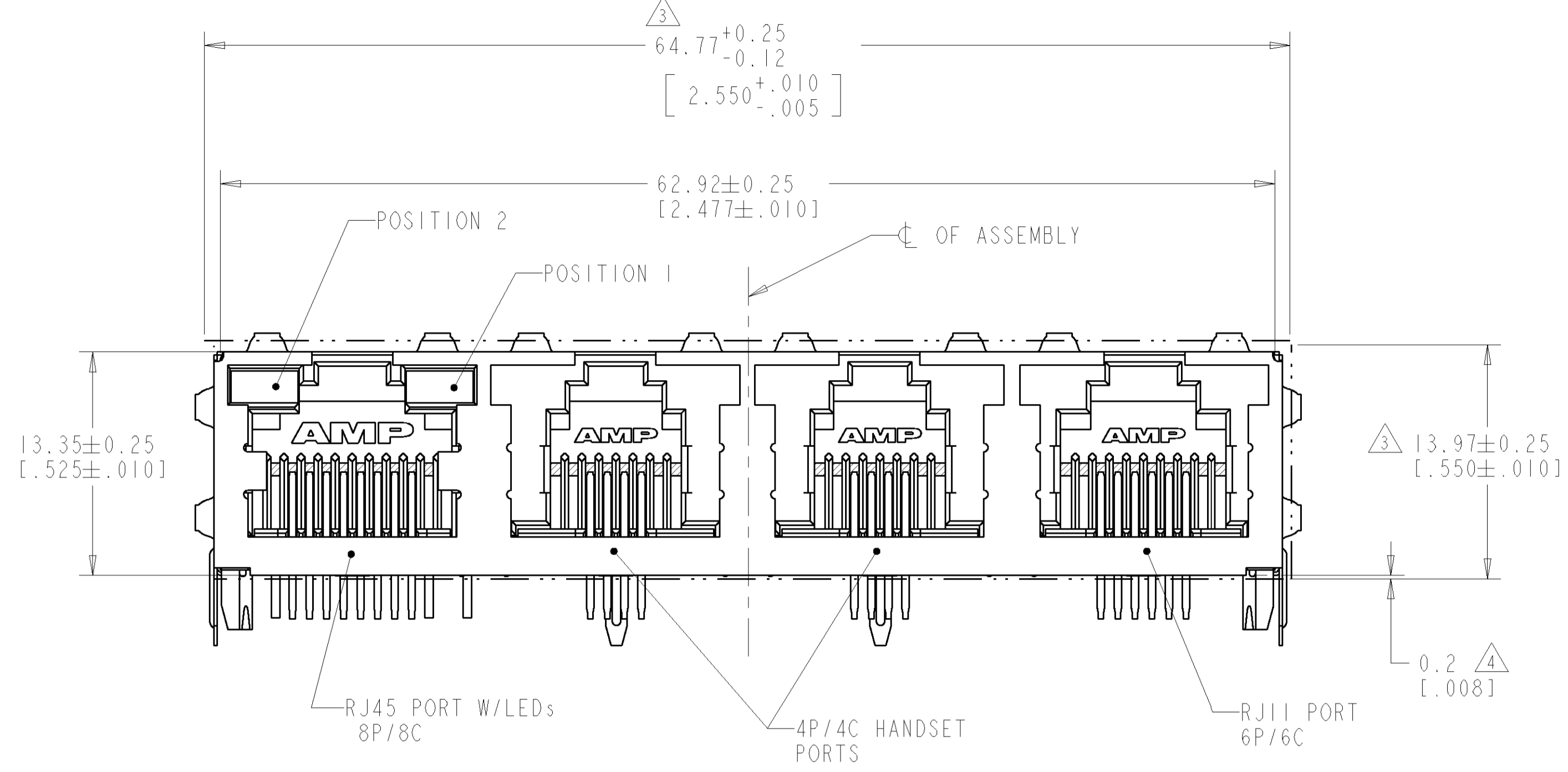
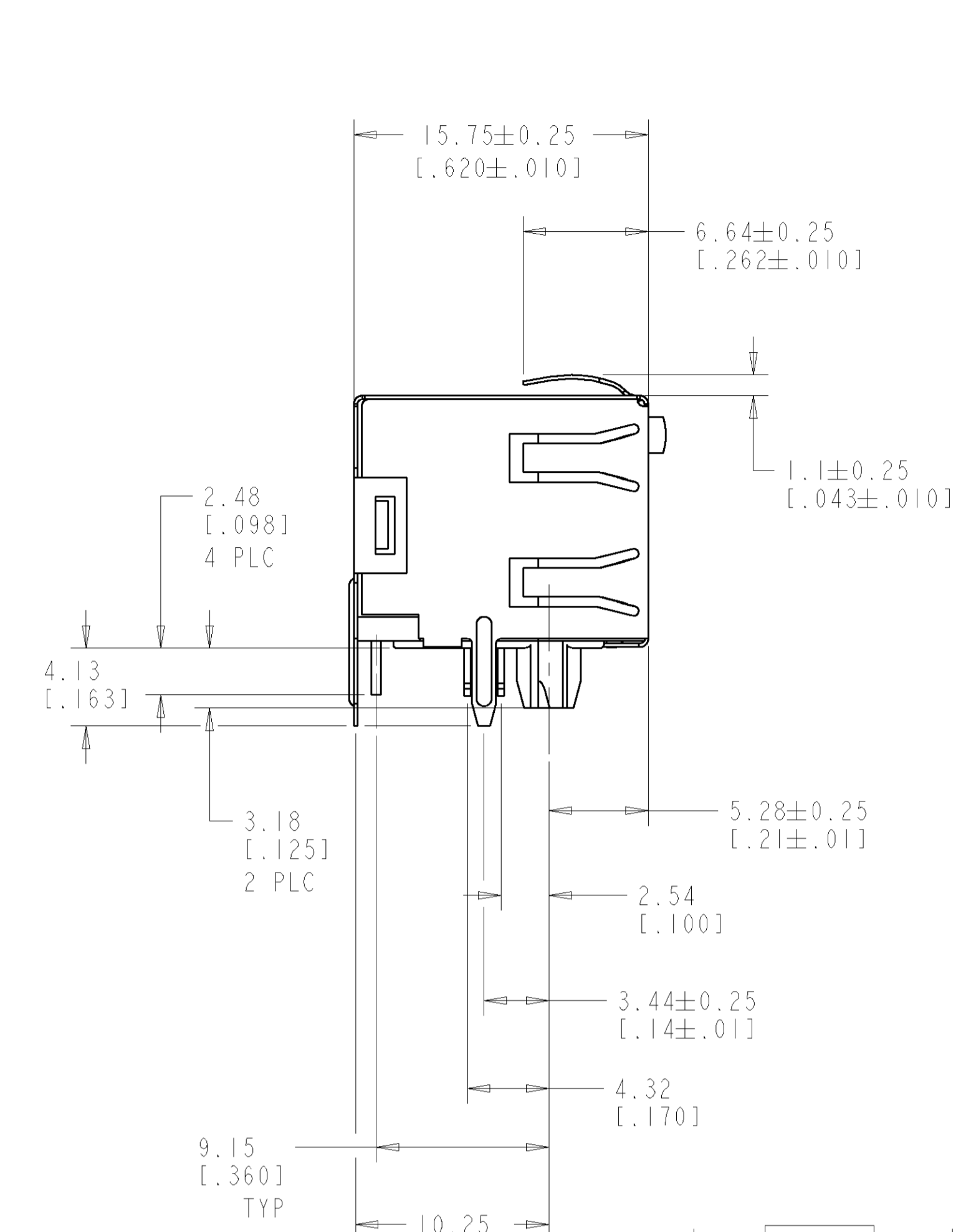
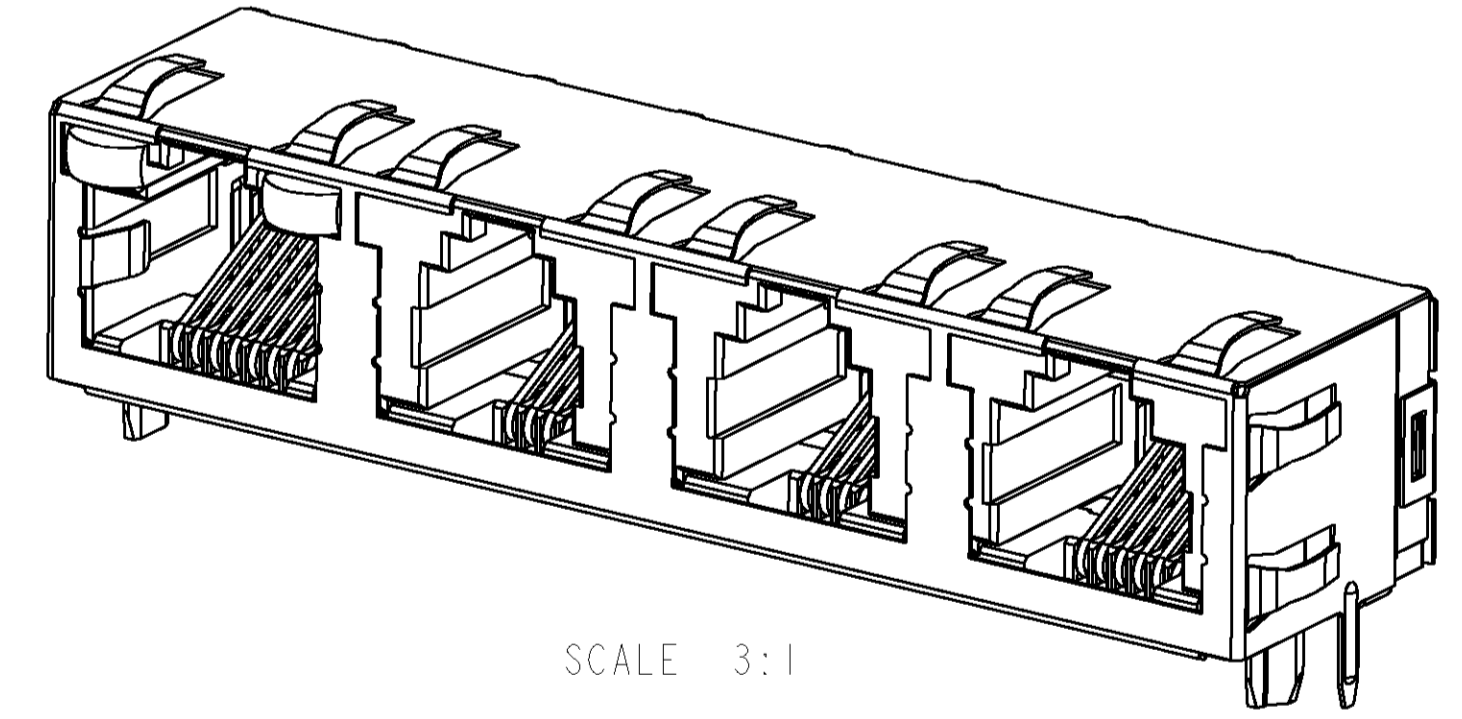


LOC	DIST	REV	DESCRIPTION	DATE	BY	APPD
AA	22	A	RELEASED PER ECOS11-0201-04	24DEC04	DRR	SF



- △ MATERIAL: HOUSING - HIGH TEMP THERMOPLASTIC, BLACK, UL94V-0.  
 TERMINALS - 0.36 [.014] THICK PHOSPHOR BRONZE PLATED WITH 3.81µm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA, 1.27µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL.  
 SHIELD - 0.196 [.0077] THICK COPPER-ZINC ALLOY PREPLATED WITH 1.27µm [.000050] MINIMUM SATIN NICKEL WITH 2.03µm [.000080] MINIMUM MATTE TIN POST DIPPED ON PCB GROUND TABS.  
 LIGHT EMITTING DIODE (LED) - DIFUSED EPOXY LENS, 0.51 x 0.51 [.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 3.56µm [.000140] NICKEL UNDERPLATE OVER 1.02µm [.000040] COPPER UNDERPLATE. POSTPLATED WITH 6.35-13.97µm [.000250-.00050] THICK TIN OVER 2.03µm [.000080] THK SILVER OVER 1.02µm [.000040] THK COPPER.
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
  - △ SUGGESTED PANEL OPENING DIMENSIONS.
  - △ SUGGESTED CLEARANCE BETWEEN BOTTOM OF CONNECTOR AND BOTTOM OF PANEL OPENING.
  - THIS MODULAR JACK WITH INTEGRATED LEDS IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)

INDICATOR COLOR	PART NUMBER
GREEN POSITION 2	2-6368144-1
ORANGE POSITION 1	

DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:		DRAWN		DATE		REV	
mm [INCHES]				BY	DATE	BY	DATE	BY	DATE
0 PLC	±	0 PLC	±	D. RINGLER	10SEP2005	J. WESTMAN	10SEP2005	S. FLICKINGER	10SEP2005
1 PLC	±.25 [.01]	1 PLC	±.25 [.01]	PRODUCT SPEC					
2 PLC	±.25 [.01]	2 PLC	±.25 [.01]	APPLICATION SPEC					
3 PLC	±.13 [.005]	3 PLC	±.13 [.005]	SIZE CAGE CODE DRAWING NO					
4 PLC	±	4 PLC	±	WEIGHT					
5 PLC	±	5 PLC	±	CUSTOMER DRAWING					
6 PLC	±	6 PLC	±	SCALE 4:1 SHEET 1 OF 1 REV A					